

OK TO ENTER: /D.G./

AMENDMENT UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
GROUP 2894  
**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q78432

Hien Boon TAN, et al.

Appln. No.: 10/721,382

Group Art Unit: 2894

Confirmation No.: 6007

Examiner: David E. Graybill

Filed: November 26, 2003

For: HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE METHOD OF  
MANUFACTURING

**AMENDMENT UNDER 37 C.F.R. § 1.116**

**MAIL STOP AF**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated October 10, 2008, please amend the above-  
identified application as follows on the accompanying pages.

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AMENDMENTS TO THE CLAIMS .....

REMARKS .....